

**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of the Claims:**

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16. (Currently Amended) An apparatus comprising:

B1 a substrate;

a chip mounted on the substrate; and

a mold cap disposed over the substrate such that the mold cap at least partially covers the chip, the mold cap having an extension extending into a corner section of the substrate, the extension extends into the corner section of the substrate without extending to an edge of the substrate.

17. (Previously Presented) The apparatus of claim 16, wherein the extension is a rib structure.

18. (Previously Presented) The apparatus of claim 16, wherein the extension extends to an edge of the substrate.

19. (Canceled) ~~The apparatus of claim 16, wherein the extension extends into the corner section of the substrate without extending to an edge of the substrate.~~

20. (Previously Presented) The apparatus of claim 16, wherein the mold cap has chamfered edges.

21. (Previously Presented) The apparatus of claim 16, comprising a plurality of solder balls on a surface of the substrate opposite the mold cap.

22. (Previously Presented) The apparatus of claim 21, comprising a plurality of solder balls on the surface of the substrate in an area of the chip.

23. (Previously Presented) The apparatus of claim 21, wherein all solder balls on the surface of the substrate are spaced from areas directly opposite an edge of the chip.

24. (Currently Amended) An apparatus comprising:

a substrate;

a chip mounted on the substrate; and

a mold cap disposed over the substrate such that the mold cap at least partially covers the chip, the mold cap having a plurality of extensions each extending into a respective corner section of the substrate, the extensions extend into the corner sections of the substrate without extending to edges of the substrate.

25. (Previously Presented) The apparatus of claim 24, wherein each extension is a rib structure.

26. (Previously Presented) The apparatus of claim 24, wherein each extension is a rounded structure.

27. (Previously Presented) The apparatus of claim 24, wherein each extension is a rounded corner of the mold cap.

28. (Previously Presented) The apparatus of claim 24, wherein at least one extension extends to an edge of the substrate.

29. (Canceled) ~~The apparatus of claim 24, wherein at least one extension extends into a respective corner section of the substrate without an edge of the substrate.~~

30. (Previously Presented) The apparatus of claim 24, wherein the mold cap has chamfered edges.

31. (Previously Presented) The apparatus of claim 24, comprising a plurality of solder balls on a surface of the substrate opposite the mold cap.

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32. (Previously Presented) The apparatus of claim 31, comprising a plurality of solder balls on the surface of the substrate in an area directly opposite the chip.

33. (Previously Presented) The apparatus of claim 31, wherein all solder balls on the surface of the substrate are spaced from areas directly opposite an edge of the chip.

34. (Currently Amended) An apparatus comprising:

a substrate;

a chip mounted on the substrate; and

a mold cap disposed over the substrate such that the mold cap at least partially covers the chip, the mold cap having an extension adjacent a corner section of the substrate, the extension extends into the corner section of the substrate without extending to an edge of the substrate.

35. (Previously Presented) The apparatus of claim 34, wherein the extension is a rib structure.

36. (Previously Presented) The apparatus of claim 34, wherein the extension is a rounded structure.

37. (Previously Presented) The apparatus of claim 34, wherein the extension is a rounded corner of the mold cap.

38. (Previously Presented) The apparatus of claim 34, wherein the mold cap has a plurality of extensions each adjacent a respective corner section of the substrate.

39. (Previously Presented) The apparatus of claim 34, wherein the mold cap has chamfered edges.

40. (Previously Presented) The apparatus of claim 34, comprising a plurality of solder balls on a surface of the substrate opposite the mold cap.

41. (Previously Presented) The apparatus of claim 40, comprising a plurality of solder balls on the surface of the substrate in an area directly opposite the chip.

42. (Previously Presented) The apparatus of claim 40, wherein all solder balls on the surface of the substrate are spaced from areas directly opposite an edge of the chip.